

[ABSTRACT]

A manufacturing method of a mounting structure, the method including: a step of preparing a mounting member including a first circuit member and a plurality of second circuit members placed on the first circuit member, the mounting member having a space between the first circuit member and the second circuit member; a step of preparing a laminate sheet including a first thermal-conductive layer and a second thermal-conductive layer, the first thermal-conductive layer disposed at least on one outermost side; a disposing step of disposing the laminate sheet on the mounting member such that the first thermal-conductive layer faces the second circuit members; and a sealing step of pressing the laminate sheet against the first circuit member and heating the laminate sheet, to seal the second circuit members so as to maintain the space, and to cure the laminate sheet. The first thermal-conductive layer after curing has a coefficient of thermal conductivity in a thickness direction at room temperature being equal to or greater than that in a principal surface direction, and the second thermal-conductive layer after curing has a coefficient of thermal conductivity in a principal surface direction at room temperature being greater than that in a thickness direction.

(Fig. 1)